

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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EPAS ID: PAT3538723

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
FEI SONG	09/08/2015
OSAMA K.A. SHANA'A	09/08/2015
YUEN HUI CHEE	09/08/2015
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<b>Name:</b>	MEDIATEK INC.
<b>Street Address:</b>	NO. 1 DUSING ROAD 1ST
<b>Internal Address:</b>	HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14862520
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	MDT-203
<b>NAME OF SUBMITTER:</b>	ZHENG JIN
<b>SIGNATURE:</b>	/zheng jin/
<b>DATE SIGNED:</b>	09/23/2015
<b>Total Attachments: 1</b>	
source=MDT-203 Assignment 090815#page1.tif	


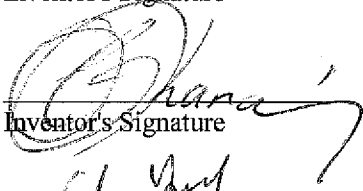

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, we, Fei Song, Osama K A Shana'a, and YuenHui Chee (hereinafter referred to as ASSIGNORS), having post office addresses of: 350 River Oaks Pkwy, Apt. 1214, San Jose, CA 95134; 550 Tyndall St. Los Altos, CA 94022; 572 Marlin Ct., Redwood City, CA 94065, U.S.A.; respectively, are the joint inventors of the invention described and claimed in the specification forming part of the United States patent application entitled "WIDEBAND HIGHLY-LINEAR LOW OUTPUT IMPEDANCE D2S BUFFER CIRCUIT," executed herewith;

WHEREAS, MEDIATEK INC. (hereafter referred to as ASSIGNEE), a corporation organized under the laws of Taiwan and having a place of business at No. 1, Dusing Rd. 1st, Hsinchu Science Park, Hsin-Chu 300, Taiwan, is desirous of acquiring the entire right, title, and interest in and to the invention and in and to any letters patents that may be granted thereof in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign, and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention, said application and any and all letters patents which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty, or otherwise, said invention, application and all letters patents on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors an assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer, and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patents on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patents on said invention, for litigation regarding said letters patents, or for the purpose of protecting title to said invention or letters patents therefor.

IN WITNESS WHEREOF, We have hereunto signed our names on the day and year set forth below.

 _____ Inventor's Signature	Fei Song _____ Inventor's Printed Name	9/8/2015 _____ Date
 _____ Inventor's Signature	Osama K A Shana'a _____ Inventor's Printed Name	9/8/2015 _____ Date
 _____ Inventor's Signature	YuenHui Chee _____ Inventor's Printed Name	9/8/2015 _____ Date